A
y —

Application No.	Applicant(s)	—— -
10/814,804	HARADA ET AL.	
Examiner	Art Unit	
I Ishwar (I. B.) Patel	2841	

Notice of Allowability		Examiner	Art Unit	
		Ishwar (I. B.) Patel	2841	
All claims being allowable, PROS herewith (or previously mailed), a	ECUTION ON THE MERITS IS Notice of Allowance (PTOL-85)	ars on the cover sheet with the co (OR REMAINS) CLOSED in this app or other appropriate communication GHTS. This application is subject to	orrespondence addro olication. If not include will be mailed in due	ed course. THIS
of the Office or upon petition by th	ne applicant. See 37 CFR 1.313	and MPEP 1308.		
1. This communication is resp	oonsive to <u>response filed on Aug</u>	<u>ust 26, 2005</u> .		
2. The allowed claim(s) is/are	<u>1-7</u> .			
	c) None of the:			
·	s of the priority documents have			
3. Copies of the c	certified copies of the priority docureau (PCT Rule 17.2(a)).	been received in Application Nocuments have been received in this i		tion from the
Applicant has THREE MONTHS noted below. Failure to timely c THIS THREE-MONTH PERIOD	omply will result in ABANDONM	of this communication to file a reply of ENT of this application.	complying with the red	quirements
		tted. Note the attached EXAMINER' s reason(s) why the oath or declara		OTICE OF
5. CORRECTED DRAWINGS	(as "replacement sheets") mus	t be submitted.		
(a) ☐ including changes requ	uired by the Notice of Draftspers	on's Patent Drawing Review (PTO-	948) attached	
•	to Paper No./Mail Date			
(b) ☐ including changes requ Paper No./Mail Date _		s Amendment / Comment or in the O	ffice action of	
ldentifying indicia such as the a each sheet. Replacement sheet	pplication number (see 37 CFR 1. (s) should be labeled as such in th	84(c)) should be written on the drawin ne header according to 37 CFR 1.121(c	gs in the front (not the i).	back) of
		sit of BIOLOGICAL MATERIAL n FOR THE DEPOSIT OF BIOLOGICA		Vote the
Attachment(s) 1. ☑ Notice of References Cited ((PTO-892)	5. ☐ Notice of Informal Pa	atent Application (PT0	D-152)
2. Notice of Draftperson's Pate	nt Drawing Review (PTO-948)	6. Interview Summary	(PTO-413),	•
3. ☑ Information Disclosure State Paper No./Mail Date 4/1/04		Paper No./Mail Date 8), 7. ⊠ Examiner's Amendm	e nent/Comment	
4. ☐ Examiner's Comment Regar of Biological Material		8. X Examiner's Stateme	nt of Reasons for Allo	wance
or biological Material		9. Other		

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

The application has been amended as follows: Cancel claims 8 and 9, not elected without traverse.

2. The following is an examiner's statement of reasons for allowance: A multilayer printed circuit board structure with a limitation "wherein the surface conductive pattern has a surface roughness on an insulation substrate side, the surface roughness of the surface conductive pattern being larger than that of the inner conductive pattern", in conjunction with other claimed limitation has not been disclosed or suggested by prior art of record.

To roughen the surface of the conductive layer or the insulating layer for better adhesion is known in the art, however, the structure where the surface conductive pattern with surface roughness larger (surface roughness towards the insulating layer) than that of the inner conductive pattern has not been disclosed. The following are the closest prior art located by the examiner.

Hirose et al., US Patent Application Publication No. 2001/0042637, discloses a circuit board with surface roughness either on the insulating layer or on the copper

Application/Control Number: 10/814,804

Art Unit: 2841

layer, (column 19, paragraph 372), but does not disclose the relationship between the roughness as claimed.

Nakatani et al., US Patent No. 6,734,542 discloses a module and states that roughening the electric insulating layer before carrying out the electroless copper-plating, the adhesive strength of the copper wiring pattern can be enhanced, (column 12, line 54-57).

Asai et al., US Patent No. 6,534,723 discloses a multilayer circuit board and states that conductor circuits are roughened to improve adhesion to adhesive and prevent delamination, but does not disclose the relationship as claimed.

Urasaki et al., US Patent No. 5,403,672, in figure 1, discloses a metal foil with surface roughness for printed circuit board.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

3. Claims 1 directed to an allowable product. Claims 4-7, previously withdrawn from consideration as a result of a restriction requirement, depend from (directly or indirectly) and include all the limitations of the allowable claim 1, is now subject to being rejoined. Claims 4-7 hereby rejoined and fully examined for patentability under 37 CFR 1.104.

Art Unit: 2841

Since claims 4-7 previously withdrawn from consideration under 37 CFR 1.142 have been rejoined, the restriction requirement made in the Office action mailed on July 13, 2005 is hereby withdrawn.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ishwar (I. B.) Patel whose telephone number is (571) 272 1933. The examiner can normally be reached on M-F (8:30 - 5:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on (571) 272 1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Kauleo EDE 2841

IBP

October 2, 2005